

WHAT IS CLAIMED IS:

1. A baking apparatus for use in baking semiconductor wafers, said apparatus comprising:

a chamber having an open upper part, and a hot plate disposed in said chamber and configured to support a wafer thereon;

a cover covering the upper part of said chamber, said cover having an inner surface confronting said hot plate; and

a film extending over the inner surface of said cover which increases the rate of formation of a uniform temperature distribution in the chamber.

2. The apparatus of claim 1, wherein said film is a film of metal having a polished surface facing said hot plate.

3. The apparatus of claim 1, wherein said film comprises a material selected from the group consisting of aluminum, brass, copper, gold and silver.

4. The apparatus of claim 2, wherein said film comprises a material selected from the group consisting of aluminum, brass, copper, gold and silver.

5. The apparatus of claim 1, wherein said film consists of material having an emissivity of 0.02 ~ 0.05.